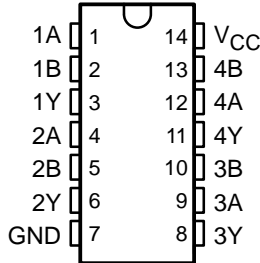


SN54AHCT00, SN74AHCT00 QUADRUPLE 2-INPUT POSITIVE-NAND GATES

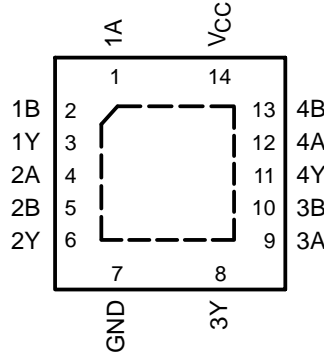
SCLS229K – OCTOBER 1995 – REVISED JULY 2003

- Inputs Are TTL-Voltage Compatible
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)

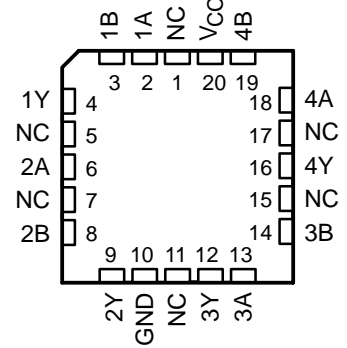
SN54AHCT00 . . . J OR W PACKAGE
SN74AHCT00 . . . D, DB, DGV, N, NS,
OR PW PACKAGE
(TOP VIEW)



SN74AHCT00 . . . RGY PACKAGE
(TOP VIEW)



SN54AHCT00 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description/ordering information

The 'AHCT00 devices perform the Boolean function $Y = \overline{A \cdot B}$ or $Y = \overline{A} + \overline{B}$ in positive logic.

ORDERING INFORMATION

| T _A | PACKAGE† | | ORDERABLE PART NUMBER | TOP-SIDE MARKING |
|----------------|---------------|---------------|-----------------------|------------------|
| | | | | |
| –40°C to 85°C | QFN – RGY | Tape and reel | SN74AHCT00RGYR | HB00 |
| | PDIP – N | Tube | SN74AHCT00N | SN74AHCT00N |
| | SOIC – D | Tube | SN74AHCT00D | AHCT00 |
| | | Tape and reel | SN74AHCT00DR | |
| | SOP – NS | Tape and reel | SN74AHCT00NSR | AHCT00 |
| | SSOP – DB | Tape and reel | SN74AHCT00DBR | HB00 |
| | TSSOP – PW | Tube | SN74AHCT00PW | HB00 |
| Tape and reel | | SN74AHCT00PWR | | |
| TVSOP – DGV | Tape and reel | SN74AHCT00DGV | HB00 | |
| –55°C to 125°C | CDIP – J | Tube | SNJ54AHCT00J | SNJ54AHCT00J |
| | CFP – W | Tube | SNJ54AHCT00W | SNJ54AHCT00W |
| | LCCC – FK | Tube | SNJ54AHCT00FK | SNJ54AHCT00FK |

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE (each gate)

| INPUTS | | OUTPUT |
|--------|---|--------|
| A | B | Y |
| H | H | L |
| L | X | H |
| X | L | H |



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS
INSTRUMENTS**

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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

SN54AHCT00, SN74AHCT00 QUADRUPLE 2-INPUT POSITIVE-NAND GATES

SCLS229K – OCTOBER 1995 – REVISED JULY 2003

recommended operating conditions (see Note 4)

| | | SN54AHCT00 | | SN74AHCT00 | | UNIT |
|-----------------|------------------------------------|------------|-----------------|------------|-----------------|------|
| | | MIN | MAX | MIN | MAX | |
| V _{CC} | Supply voltage | 4.5 | 5.5 | 4.5 | 5.5 | V |
| V _{IH} | High-level input voltage | 2 | | 2 | | V |
| V _{IL} | Low-level input voltage | | 0.8 | | 0.8 | V |
| V _I | Input voltage | 0 | 5.5 | 0 | 5.5 | V |
| V _O | Output voltage | 0 | V _{CC} | 0 | V _{CC} | V |
| I _{OH} | High-level output current | | -8 | | -8 | mA |
| I _{OL} | Low-level output current | | 8 | | 8 | mA |
| Δt/Δv | Input transition rise or fall rate | | 20 | | 20 | ns/V |
| T _A | Operating free-air temperature | -55 | 125 | -40 | 85 | °C |

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | V _{CC} | T _A = 25°C | | | SN54AHCT00 | | SN74AHCT00 | | UNIT |
|--------------------|---|-----------------|-----------------------|-----|------|------------|------|------------|-----|------|
| | | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| V _{OH} | I _{OH} = -50 μA | 4.5 V | 4.4 | 4.5 | | 4.4 | | 4.4 | V | |
| | I _{OH} = -8 mA | | 3.94 | | | 3.8 | | 3.8 | | |
| V _{OL} | I _{OL} = 50 μA | 4.5 V | | | 0.1 | | 0.1 | 0.1 | V | |
| | I _{OL} = 8 mA | | | | 0.36 | | 0.44 | 0.44 | | |
| I _I | V _I = 5.5 V or GND | 0 V to 5.5 V | | | ±0.1 | | ±1* | ±1 | μA | |
| I _{CC} | V _I = V _{CC} or GND, I _O = 0 | 5.5 V | | | 2 | | 20 | 20 | μA | |
| ΔI _{CC} † | One input at 3.4 V, Other inputs at V _{CC} or GND | 5.5 V | | | 1.35 | | 1.5 | 1.5 | mA | |
| C _i | V _I = V _{CC} or GND | 5 V | | 2 | 10 | | | 10 | pF | |

* On products compliant to MIL-PRF-38535, this parameter is not production tested at V_{CC} = 0 V.

† This is the increase in supply current for each input at one of the specified TTL voltage levels, rather than 0 V or V_{CC}.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | LOAD CAPACITANCE | T _A = 25°C | | | SN54AHCT00 | | SN74AHCT00 | | UNIT |
|------------------|--------------|-------------|------------------------|-----------------------|-------|-----|------------|-----|------------|-----|------|
| | | | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| t _{PLH} | A or B | Y | C _L = 15 pF | 5** | 6.9** | | 1** | 8** | 1 | 8 | ns |
| t _{PHL} | | | | 5** | 6.9** | | 1** | 8** | 1 | 8 | |
| t _{PLH} | A or B | Y | C _L = 50 pF | 5.5 | 7.9 | | 1 | 9 | 1 | 9 | ns |
| t _{PHL} | | | | 5.5 | 7.9 | | 1 | 9 | 1 | 9 | |

** On products compliant to MIL-PRF-38535, this parameter is not production tested.

SN54AHCT00, SN74AHCT00 QUADRUPLE 2-INPUT POSITIVE-NAND GATES

SCLS229K – OCTOBER 1995 – REVISED JULY 2003

noise characteristics, $V_{CC} = 5\text{ V}$, $C_L = 50\text{ pF}$, $T_A = 25^\circ\text{C}$ (see Note 5)

| PARAMETER | SN74AHCT00 | | | UNIT |
|--|------------|------|------|------|
| | MIN | TYP | MAX | |
| $V_{OL(P)}$ Quiet output, maximum dynamic V_{OL} | | 0.4 | 0.8 | V |
| $V_{OL(V)}$ Quiet output, minimum dynamic V_{OL} | | -0.4 | -0.8 | V |
| $V_{OH(V)}$ Quiet output, minimum dynamic V_{OH} | | 4.5 | | V |
| $V_{IH(D)}$ High-level dynamic input voltage | 2 | | | V |
| $V_{IL(D)}$ Low-level dynamic input voltage | | | 0.8 | V |

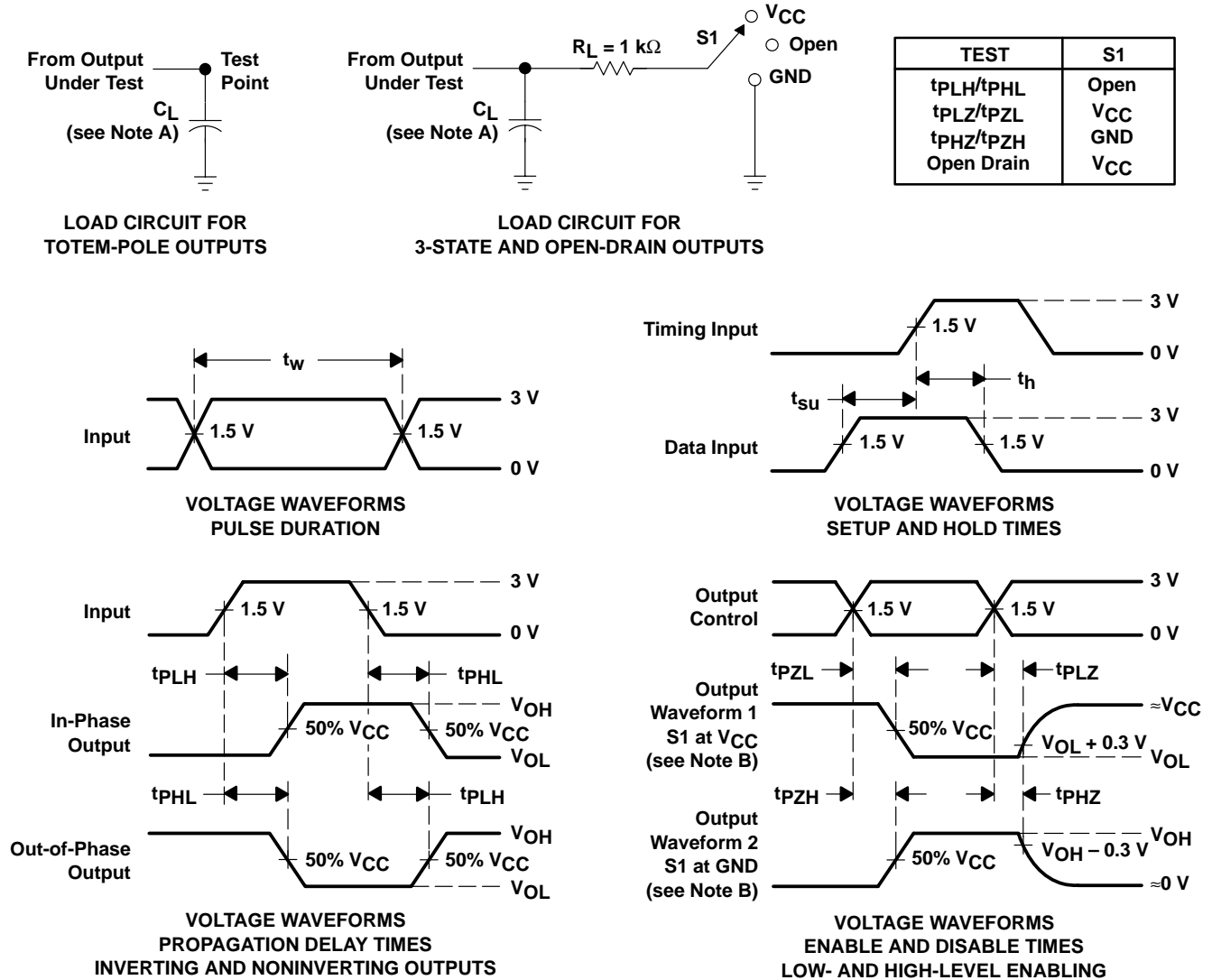
NOTE 5: Characteristics are for surface-mount packages only.

operating characteristics, $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

| PARAMETER | TEST CONDITIONS | TYP | UNIT |
|--|-----------------------------|------|------|
| C_{pd} Power dissipation capacitance | No load, $f = 1\text{ MHz}$ | 10.5 | pF |



PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1\text{ MHz}$, $Z_O = 50\ \Omega$, $t_r \leq 3\text{ ns}$, $t_f \leq 3\text{ ns}$.
 D. The outputs are measured one at a time with one input transition per measurement.
 E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|--------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| 5962-9682301Q2A | ACTIVE | LCCC | FK | 20 | 1 | TBD | Call TI | Level-NC-NC-NC |
| 5962-9682301QCA | ACTIVE | CDIP | J | 14 | 1 | TBD | Call TI | Level-NC-NC-NC |
| 5962-9682301QDA | ACTIVE | CFP | W | 14 | 1 | TBD | Call TI | Level-NC-NC-NC |
| SN74AHCT00D | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74AHCT00DBLE | OBSOLETE | SSOP | DB | 14 | | TBD | Call TI | Call TI |
| SN74AHCT00DBR | ACTIVE | SSOP | DB | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74AHCT00DBRE4 | ACTIVE | SSOP | DB | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74AHCT00DE4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74AHCT00DGVR | ACTIVE | TVSOP | DGV | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74AHCT00DGVRE4 | ACTIVE | TVSOP | DGV | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74AHCT00DR | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74AHCT00DRE4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74AHCT00N | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | Level-NC-NC-NC |
| SN74AHCT00NE4 | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | Level-NC-NC-NC |
| SN74AHCT00NSR | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74AHCT00NSRE4 | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74AHCT00PW | ACTIVE | TSSOP | PW | 14 | 90 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74AHCT00PWE4 | ACTIVE | TSSOP | PW | 14 | 90 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74AHCT00PWG4 | ACTIVE | TSSOP | PW | 14 | 90 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74AHCT00PWLE | OBSOLETE | TSSOP | PW | 14 | | TBD | Call TI | Call TI |
| SN74AHCT00PWR | ACTIVE | TSSOP | PW | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74AHCT00PWRE4 | ACTIVE | TSSOP | PW | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74AHCT00PWRG4 | ACTIVE | TSSOP | PW | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74AHCT00RGYR | ACTIVE | QFN | RGY | 14 | 1000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1YEAR |
| SN74AHCT00RGYRG4 | ACTIVE | QFN | RGY | 14 | 1000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1YEAR |
| SNJ54AHCT00FK | ACTIVE | LCCC | FK | 20 | 1 | TBD | Call TI | Level-NC-NC-NC |
| SNJ54AHCT00J | ACTIVE | CDIP | J | 14 | 1 | TBD | Call TI | Level-NC-NC-NC |
| SNJ54AHCT00W | ACTIVE | CFP | W | 14 | 1 | TBD | Call TI | Level-NC-NC-NC |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



| DIM \ PINS ** | 14 | 16 | 18 | 20 |
|---------------|------------------------|------------------------|------------------------|------------------------|
| A | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC |
| B MAX | 0.785 (19,94) | .840 (21,34) | 0.960 (24,38) | 1.060 (26,92) |
| B MIN | — | — | — | — |
| C MAX | 0.300 (7,62) | 0.300 (7,62) | 0.310 (7,87) | 0.300 (7,62) |
| C MIN | 0.245 (6,22) | 0.245 (6,22) | 0.220 (5,59) | 0.245 (6,22) |

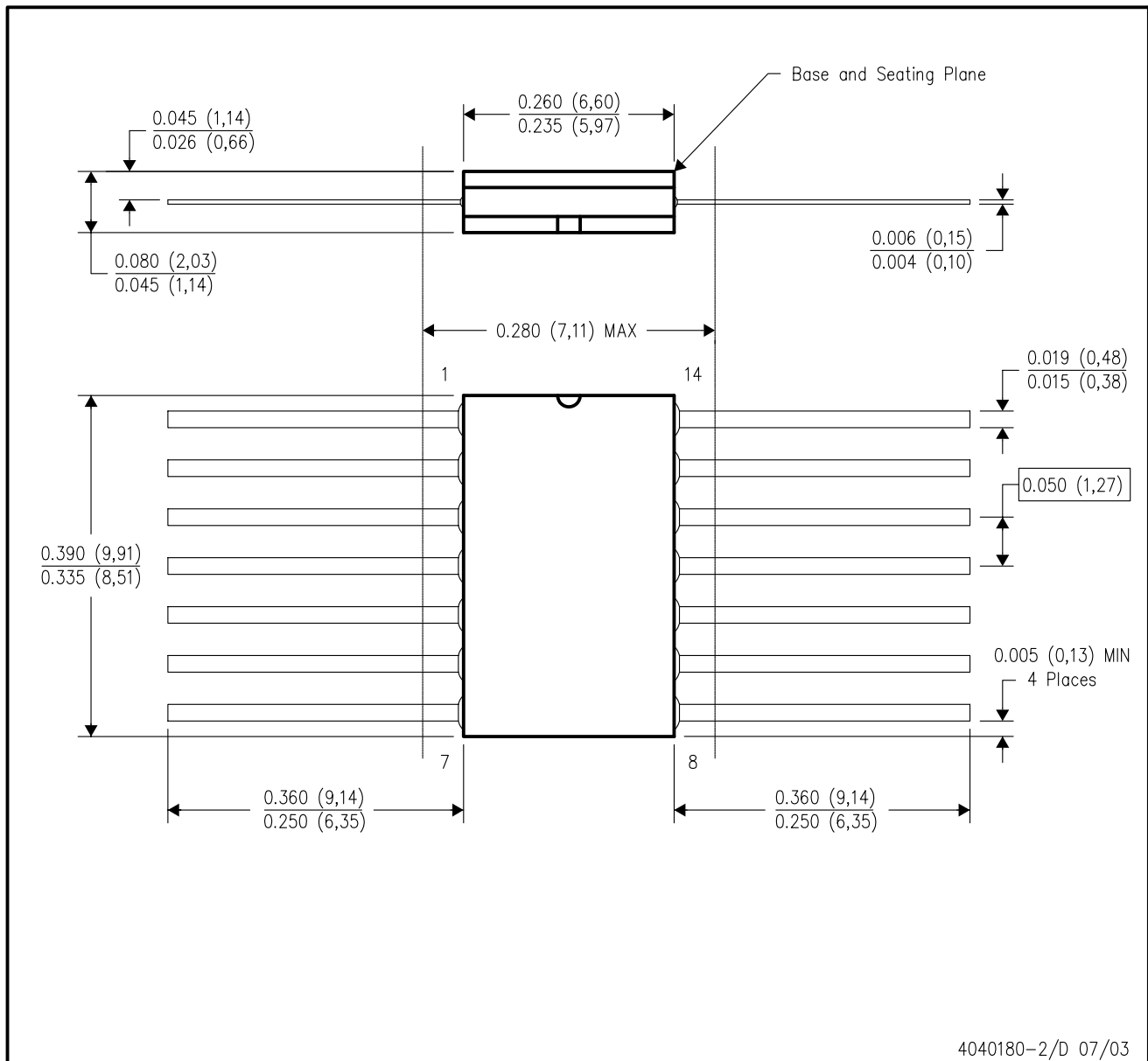


4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



4040180-2/D 07/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



4040140/D 10/96

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a metal lid.
 - D. The terminals are gold plated.
 - E. Falls within JEDEC MS-004

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

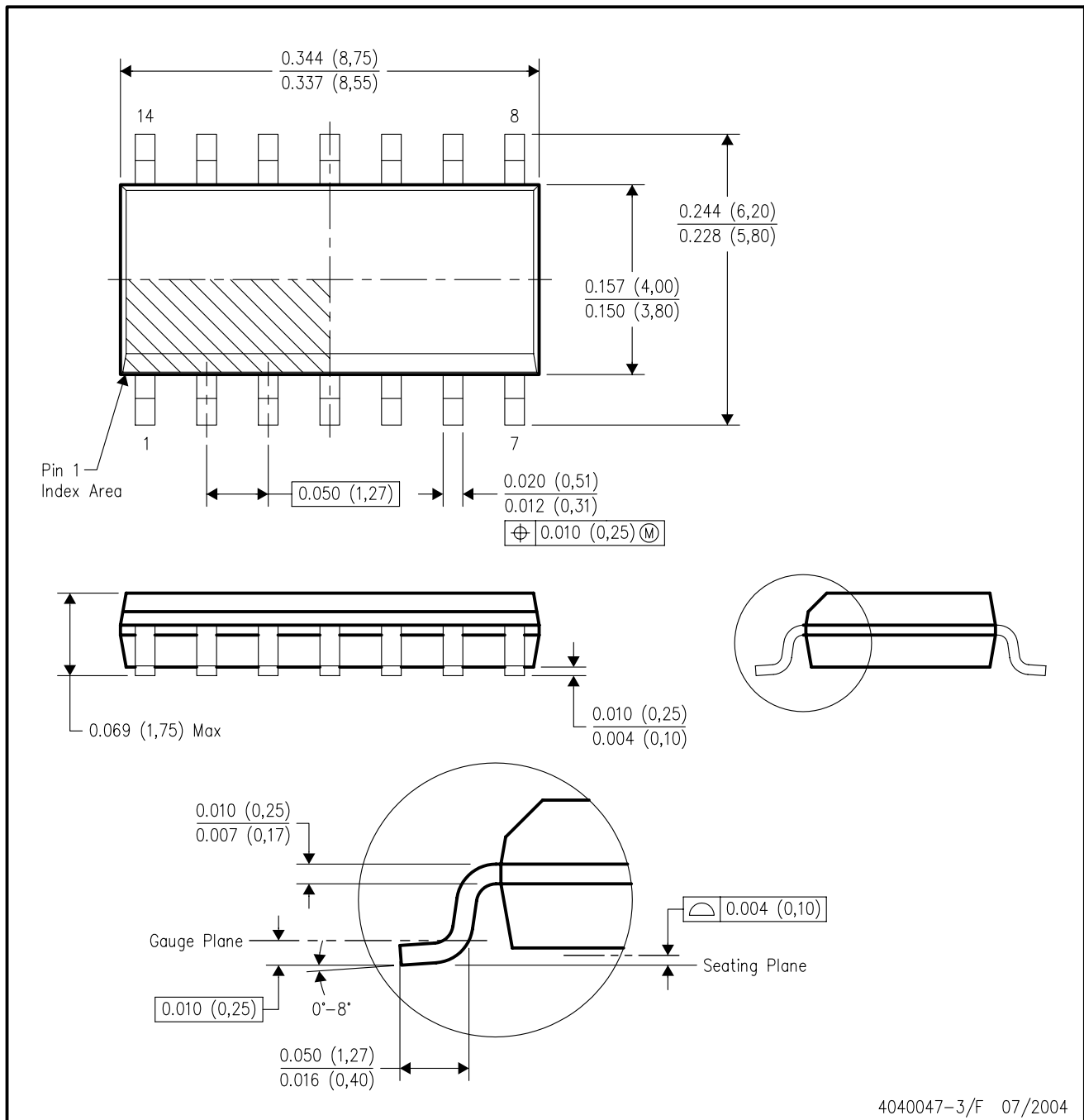
24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194

D (R-PDSO-G14)

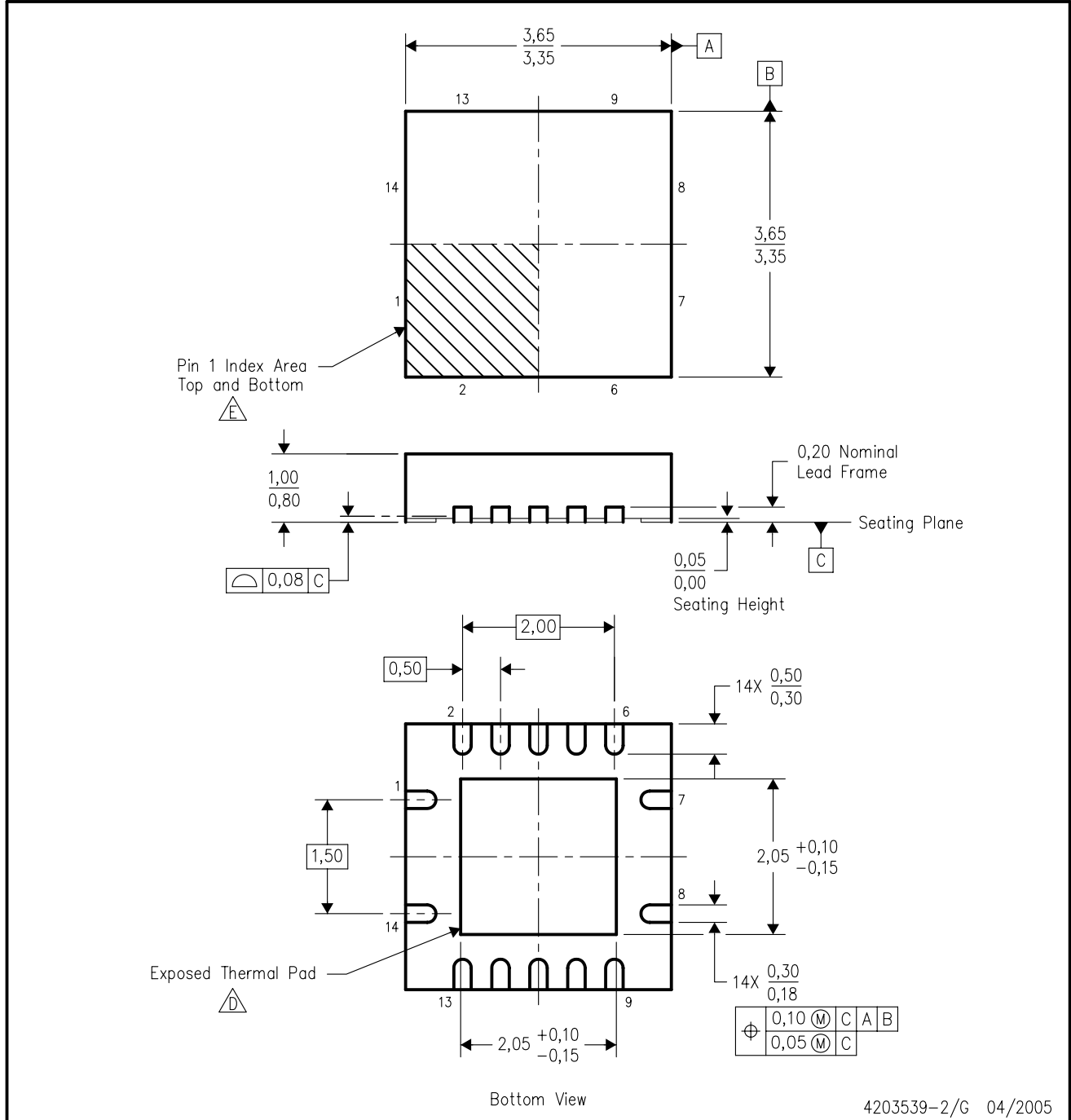
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MS-012 variation AB.

RGY (S-PQFP-N14)

PLASTIC QUAD FLATPACK



4203539-2/G 04/2005

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. QFN (Quad Flatpack No-Lead) package configuration.
 - The package thermal pad must be soldered to the board for thermal and mechanical performance.
 - Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.
 - F. Package complies to JEDEC MO-241 variation BA.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



4040064/F 01/97

- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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